



2811

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Practitioner's Document No. U-013887-9

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Sung-Fei WANG, et al  
Serial No.: 10/087,432  
Filed: March 1, 2002  
For: STACKED SEMICONDUCTOR CHIP PACKAGE

Group No.: 2811  
Examiner:

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Assistant Commissioner for Patents  
Washington, D.C. 20231

TRANSMITTAL OF SUBSTITUTE SPECIFICATION (37 C.F.R. 1.125)

NOTE: A substitute specification, excluding the claims, may be filed at any point up to payment of the issue fee if it is accompanied by items indicated below. See 37 CFR 1.125(b).

1. Enclosed is a substitute specification for the originally filed specification in this application.

NOTE: The substitute specification must be submitted in clean form without markings as to amended material. 37 CFR 1.125(c).

2. (complete the following applicable item)

[ ] This substitute specification is submitted in response to a requirement by the Examiner.

OR

[X] This substitute specification is being voluntarily submitted, in order to facilitate the processing of the application.

CERTIFICATE OF MAILING/TRANSMISSION (37 C.F.R. 1.8(a))

I hereby certify that, on the date shown below, this correspondence is being:

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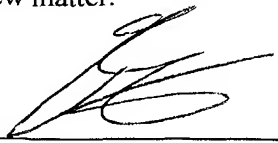
Signature

WILLIAM R. EVANS  
(type or print name of person certifying)

Date: April 24, 2002

3. No marked-up copy of the substitute specification showing the matter being added to and the matter being deleted from the specification is attached because the substitute specification is being provided only as a clearer copy.

4. Accompanying this transmittal is a statement, as required by 37 C.F.R. 1.125, that the substitute specification transmitted herewith contains no new matter.



**SIGNATURE OF PRACTITIONER**

Reg. No. 25,858

WILLIAM R. EVANS

*(Type or print name of practitioner)*

Tel. No.: (212) 708-1945

P.O. Address  
c/o Ladas & Parry  
26 West 61 Street  
New York, NY 10023

Customer No.: 00140



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STATEMENT THAT SUBSTITUTE SPECIFICATION  
CONTAINS NO NEW MATTER (37 C.F.R. 1.125)

1. Identification of person making this statement

William R. Evans  
(type or print name)

Ladas & Parry  
26 West 61 Street  
New York, NY 10023

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The person making this statement is:

(complete applicable item)

- [ ] the inventor in this application.  
[X] the attorney in this application, Registration Number \_\_\_\_\_  
[ ] other (indicate relationship)

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Date: April 24, 2002

WILLIAM R. EVANS  
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## 2. Statement

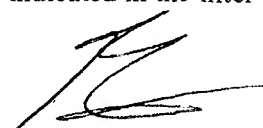
I hereby state that the accompanying substitute specification contains no new matter over that contained in the above-identified application originally filed.

*(complete the following, if applicable)*

☐ I further state that the changes made are the same as indicated in the inter-lineated substitute specification also accompanying this statement.

April 24, 2002

Date

  
\_\_\_\_\_  
Signature of person making statement  
WILLIAM R. EVANS